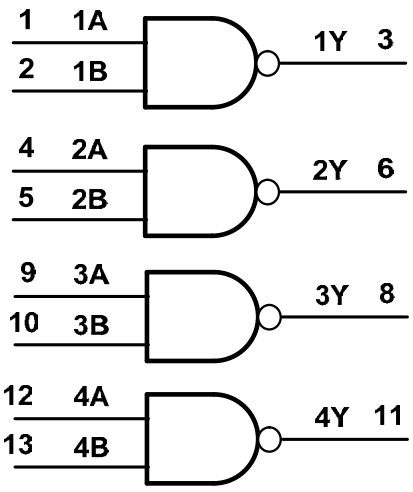
Pin Descriptions

Pin Number	Pin Name	Function
1	1A	Data Input
2	1B	Data Input
3	1Y	Data Output
4	2A	Data Input
5	2B	Data Input
6	2Y	Data Output
7	GND	Ground
8	3Y	Data Output
9	3A	Data Input
10	3B	Data Input
11	4Y	Data Output
12	4A	Data Input
13	4B	Data Input
14	V_{CC}	Supply Voltage

Logic Diagram



Fuction Table

Inputs		Output
A	B	Y
L	L	H
L	H	H
H	L	H
H	H	L

Absolute Maximum Ratings (Note 4) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
V_{CC}	Supply Voltage Range	-0.5 to 6.5	V
V_I	Input Voltage Range	-0.5 to 6.5	V
V_O	Voltage applied to output in high impedance or I_{OFF} state	-0.5 to 6.5	V
V_O	Voltage applied to output in high or low state	-0.3 to V_{CC} +0.5	V
I_{IK}	Input Clamp Current $V_I < 0$	-50	mA
I_{OK}	Output Clamp Current $V_O < 0$	-50	mA
I_O	Continuous output current	±50	mA
I_{CC}, I_{GND}	Continuous current through Vcc or GND	±100	mA
T_J	Operating Junction Temperature	-40 to 150	°C
T_{STG}	Storage Temperature	-65 to 150	°C
P_{TOT}	Total Power Dissipation	500	mW

Note: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

Recommended Operating Conditions (Note 5) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	Supply Voltage		1.65	5.5	V
V_I	Input Voltage		0	5.5	V
V_O	Output Voltage	Active Mode	0	V_{CC}	V
		V_{CC}= 0V; Power Down Mode	0	5.5	V
Δt/ΔV	Input transition rise or fall rate	V_{CC} = 1.65V to 2.7V		20	ns/V
		V_{CC} = 2.7V to 3.6V		10	
T_A	Operating free-air temperature		-40	+125	°C

Notes: 5. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V_{CC}	T_A = -40°C to +85°C		T_A = -40°C to +125°C		Unit
				Min	Max	Min	Max	
V_{IH}	High-level Input Voltage		1.65V to 1.95V	0.65 X V_{CC}		0.65 X V_{CC}		V
			2.3V to 2.7V	1.7		1.6		
			2.7 V to 3.6V	2.0		2.0		
V_{IL}	Low-level input voltage		1.65V to 1.95V		0.35 X V_{CC}		0.35 X V_{CC}	V
			2.3V to 2.7V		0.7		0.7	
			2.7V to 3.6V		0.8		0.8	
V_{OH}	High Level Output Voltage	I_{OH} = -100µA	1.65V to 3.6V	V_{CC} – 0.2		V_{CC} – 0.3		V
		I_{OH} = -4mA	1.65V	1.2				
		I_{OH} = -8mA	2.3V	1.9				
		I_{OH} = -12mA	2.7V	2.2		2.05		
			3.0V	2.3		2.1		
		I_{OH} = -24mA	3.0V	2.2		2.0		
V_{OL}	High-level Output Voltage	I_{OH} = 100µA	1.65V to 3.6V		0.2		0.3	V
		I_{OH} = 4mA	1.65V		0.45		0.6	
		I_{OH} = 8mA	2.3V		0.70		0.85	
		I_{OH} = 12mA	2.7V		0.40		0.6	
			3.0V		0.55		0.6	
		I_{OH} =-24mA	3.0V		0.55		0.6	
I_I	Input Current	V_I = GND to 5.5V	3.6V		±5		±20	µA
I_{OFF}	Power Down Leakage Current	V_I or V_O = 0V to 3.6V	0		10		20	µA
I_{CC}	Supply Current	V_I = GND or V_{CC} I_O=0	3.6V		10		40	µA
ΔI_{CC}	Additional Supply Current	One input at V_{CC} – 0.6V Other at Vcc or Gnd.	2.7V to 3.6V		500		5000	µA

Switching Characteristics

Symbol	Parameter	Test Conditions	V_{CC}	T_A = 25°C			-40°C to 85°C		-40°C to 125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t_{PD}	Propagation Delay A_N or B_N to Y_N	Figure 1	1.65V to1.95V	1.0	6.0	12.0	1.0	12.5	1.0	14.0	ns
			2.3V to 2.7V	1.0	4.6	5.9	1.0	6.4	1.0	7.9	
			2.7V	1.0	4.3	4.9	1.0	5.1	1.0	6.5	
			3V to 3.6V	1.0	3.5	4.1	1.0	4.3	1.0	5.5	
$t_{SK(0)}$	Output Skew Time		3V to 3.6V					1.0		1.5	ns

Operating Characteristics (@T_A = +25°C, unless otherwise specified.)

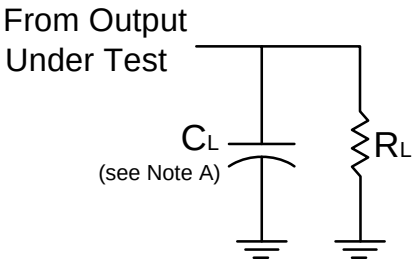
Parameter		Test Conditions	V_{CC} = 1.8V	V_{CC} = 2.5V	V_{CC} = 3.3V	Unit
			Typ	Typ	Typ	
C_{pd}	Power dissipation capacitance per gate	f = 10 MHz	17	17	18	pF
C_I	Input Capacitance	V_I = V_{CC} – or GND	4	4	4	pF

Package Characteristics

Symbol	Parameter	Test Conditions	V_{CC}	Min	Typ	Max	Unit
θ_{JA}	Thermal Resistance Junction-to-Ambient	SO-14	(Note 6)		TBD		°C/W
		TSSOP-14			159		
θ_{JC}	Thermal Resistance Junction-to-Case	SO-14	(Note 6)		TBD		°C/W
		TSSOP-14			25		

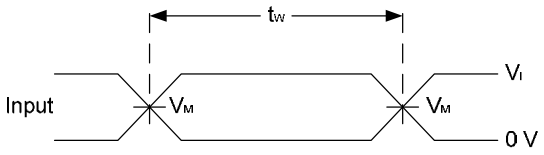
Note: 6. Test condition for SO-14 and TSSOP-14 : Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Parameter Measuement Information

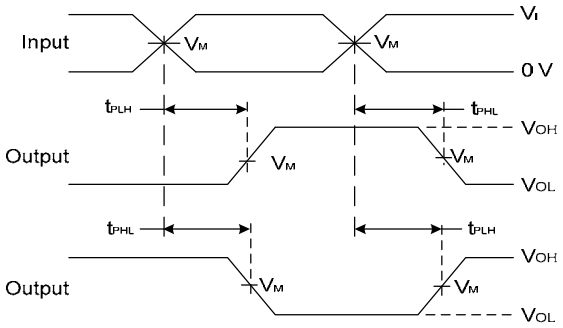


V_{CC}	Inputs		V_M	C_L	R_L
	V_I	t_r/t_f			
1.8V±0.15V	V_{CC}	≤2ns	$V_{CC}/2$	30pF	1KΩ
2.5V±0.2V	V_{CC}	≤2ns	$V_{CC}/2$	30pF	500Ω
2.7V	2.7V	≤2.5ns	1.5V	50pF	500Ω
3.3V±0.3V	2.7V	≤2.5ns	1.5V	50pF	500Ω

Parameter Measuement Information (cont.)



Voltage Waveform
Pulse Duration

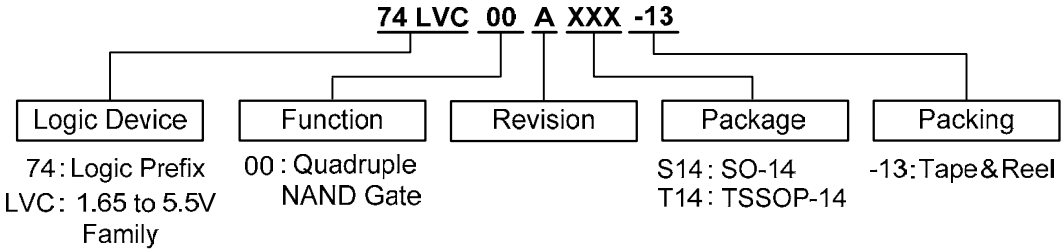


Voltage Waveform
Propagation Delay Times
Inverting and Non Inverting Outputs

Notes: A . Includes test lead and test apparatus capacitance.
B. All pulses are supplied at pulse repetition rate ≤ 10 MHz
C. Inputs are measured separately one transition per measurement
D. t_{PLH} and t_{PHL} are the same as t_{PD}

Figure 1. Load Circuit and Voltage Waveforms

Ordering Information

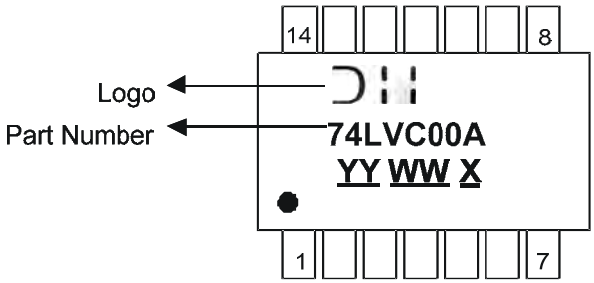


Part Number	Package Code	Packaging (Note 7)	13" Tape and Reel	
			Quantity	Part Number Suffix
74LVC00AS14-13	S14	SO-14	2500/Tape & Reel	-13
74LVC00AT14-13	T14	TSSOP-14	2500/Tape & Reel	-13

Notes: 7. The taping orientation and tape details can be found at http://www.diodes.com/datasheets/ap02007.pdf

Marking Information

(1) SO-14, TSSOP-14

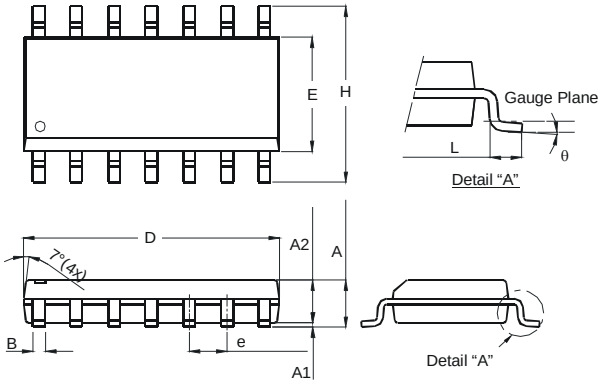


YY : Year : 08, 09,10~
WW : Week : 01~52; 52 represents 52 and 53 week
X : Internal Code

Part Number	Package
74LVC00AS14	SO-14
74LVC00AT14	TSSOP-14

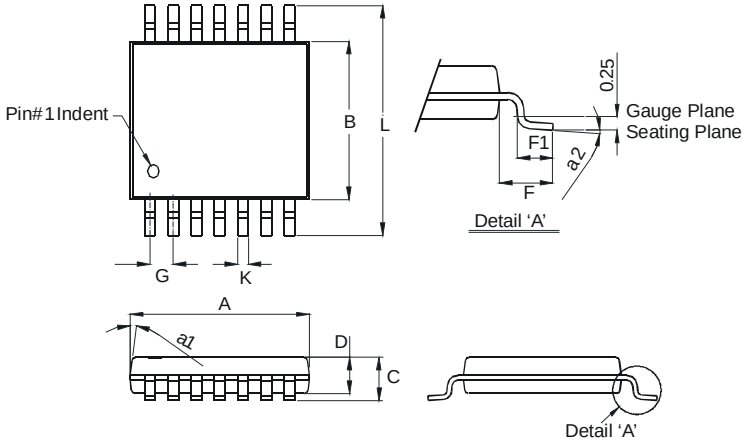
Package Outline Dimensions (All dimensions in mm.)

Package Type: SO-14



SO-14		
Dim	**Min**	**Max**
A	1.47	1.73
A1	0.10	0.25
A2	1.45 Typ	
B	0.33	0.51
D	8.53	8.74
E	3.80	3.99
e	1.27 Typ	
H	5.80	6.20
L	0.38	1.27
θ	0°	8°
All Dimensions in mm		

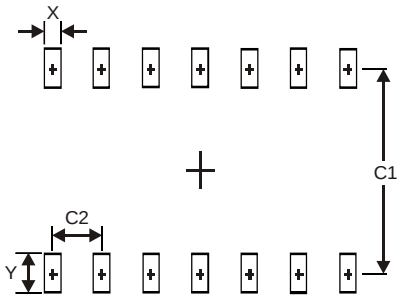
Package Type: TSSOP-14



TSSOP-14		
Dim	**Min**	**Max**
a1	7° (4X)	
a2	0°	8°
A	4.9	5.10
B	4.30	4.50
C	—	1.2
D	0.8	1.05
F	1.00 Typ	
F1	0.45	0.75
G	0.65 Typ	
K	0.19	0.30
L	6.40 Typ	
All Dimensions in mm		

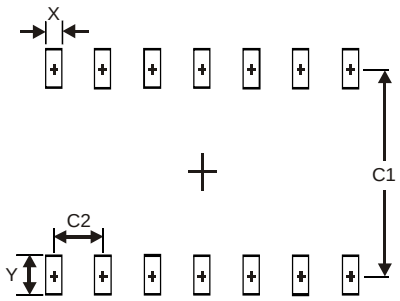
Suggested Pad Layout

Package Type: SO-14



Dimensions	Value (in mm)
X	0.60
Y	1.50
C1	5.4
C2	1.27

Package Type: TSSOP-14



Dimensions	Value (in mm)
X	0.45
Y	1.45
C1	5.9
C2	0.65

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